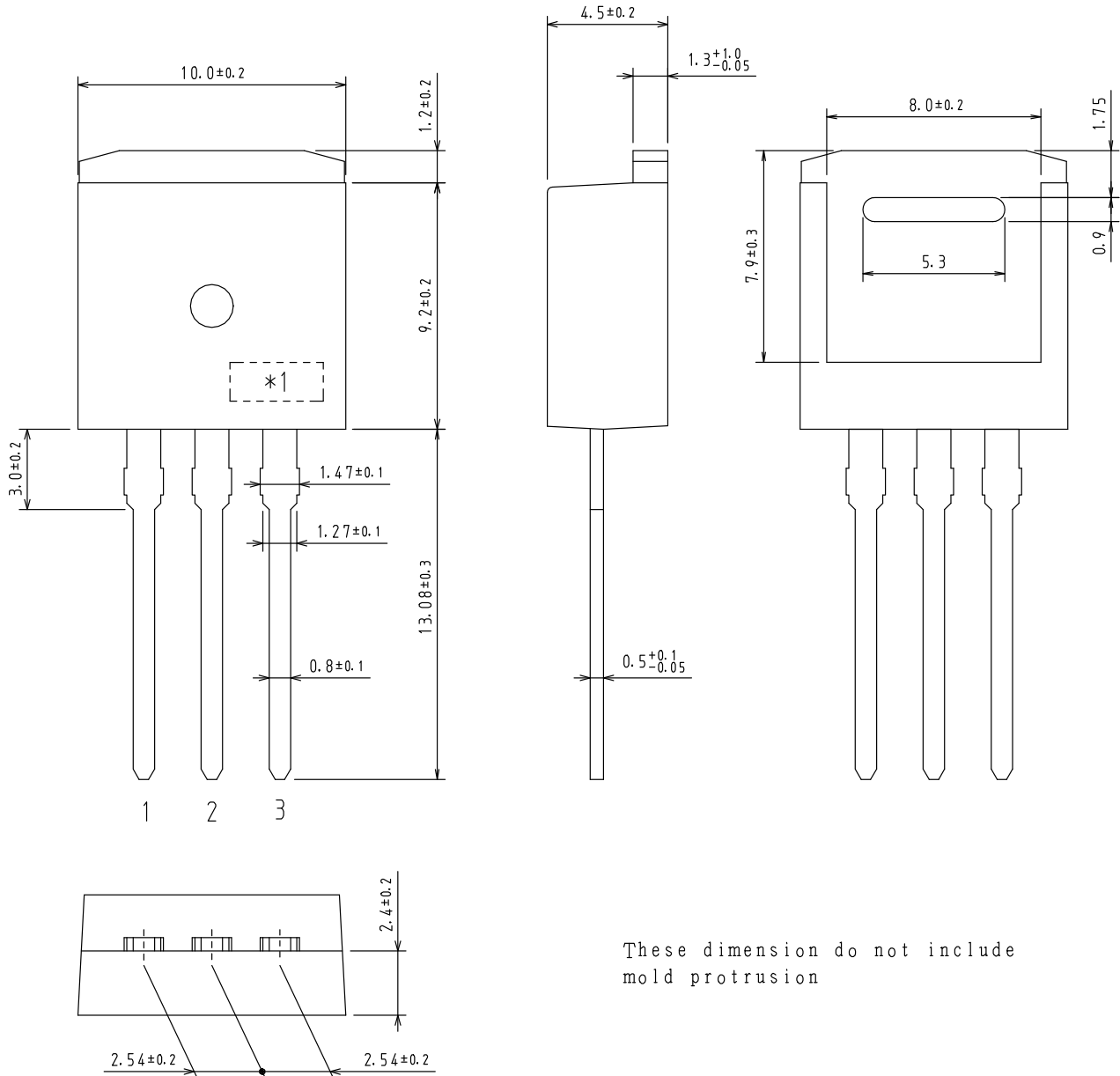


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS


I2PAK / TO-262-3L
CASE 418AN
ISSUE O

DATE 31 MAR 2012



These dimension do not include mold protrusion

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DESCRIPTION:	I2PAK / TO-262-3L	PAGE 1 OF 1

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